

Title (en)
APPARATUS FOR PLATING CYLINDER

Title (de)
VORRICHTUNG ZUR PLATTIERUNG EINES ZYLINDERS

Title (fr)
APPAREIL DE PLACAGE DE CYLINDRE

Publication
EP 2623646 A1 20130807 (EN)

Application
EP 11829066 A 20110927

Priority
• JP 2010223986 A 20101001
• JP 2011071960 W 20110927

Abstract (en)
Provided is a plating apparatus for a cylinder, which is capable of extending service life of the entire apparatus in a technology of plating a cylinder, eliminating hardness nonuniformity of a plating layer on a cylinder surface by achieving a uniform hardness, and suppressing oxidation of a tip of chuck means. The plating apparatus for a cylinder includes: a plating bath to be filled with a plating solution; chuck means for holding a long cylinder at both ends in a longitudinal direction so as to be rotated and energized, and accommodating the long cylinder in the plating bath; and a pair of opposed insoluble electrodes which is vertically installed so as to face both side surfaces of the long cylinder in the plating bath, and is supplied with a predetermined current. The chuck means includes thermal cooling means, and the thermal cooling means includes a cooling medium and causes the cooling medium to circulate to cool a cylinder holding section of the chuck means so that heat accumulation in the long cylinder, in particular, a cylinder end portion and the cylinder holding section of the chuck means is eliminated.

IPC 8 full level
C25D 7/04 (2006.01); **C25D 17/00** (2006.01); **C25D 17/06** (2006.01); **C25D 17/10** (2006.01); **C25D 21/02** (2006.01)

CPC (source: EP KR US)
C25D 7/04 (2013.01 - EP KR US); **C25D 17/005** (2013.01 - EP US); **C25D 17/06** (2013.01 - EP KR US); **C25D 17/08** (2013.01 - KR); **C25D 17/10** (2013.01 - EP US); **C25D 21/02** (2013.01 - EP US)

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
US 2013153410 A1 20130620; CN 102933751 A 20130213; CN 102933751 B 20160113; EP 2623646 A1 20130807; EP 2623646 A4 20150923; JP WO2012043513 A1 20140224; KR 20130114573 A 20131017; WO 2012043513 A1 20120405

DOCDB simple family (application)
US 201113818201 A 20110927; CN 201180027638 A 20110927; EP 11829066 A 20110927; JP 2011071960 W 20110927; JP 2012536456 A 20110927; KR 20127031254 A 20110927